## **FWL 100**

Fully-Automatic In-Line Frame and Wafer Laminating System



The FWL 100 is a flexible, fullyautomatic in-line frame and wafer laminating system for wafers up to 6" in diameter. It is the ideal solution when it comes to laminate films and very thin wafers made from brittle materials tension free at high speed and with unprecedented precision. The modular design, state-of-the-art vacuum lamination technology, user friendly machine/operator interface and material tracing system make the FWL 100 the lamination system of your choice.

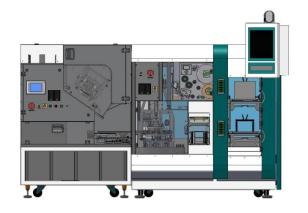
With the FWL 100, customer requirements for flexibility, speed and accuracy in opto-electronics manufacturing, high frequency

module production and semiconductor manufacturing are met better than ever.



## **FWL 100**

## Fully-Automatic Inline Frame and Wafer Laminating System





Technical Data	
Wafer frames	all industry standard types up to an overall dimension of 276mm square
Wafer frame input system	stack
Applicable films	SWT10+, SWT20+, G965 (blue), G965 (transparent), UE-115AJ, UV D-650 from roll
Film tension control	servo motor
Wafer sizes	2 inches up to 6 inches in diameter, thickness $\geq 100 \mu m$ (50 $\mu m$ - 100 $\mu m$ thickness optional)
Wafer materials	Al <sub>2</sub> O <sub>3</sub> , GaAs, GaN, SiC, Ge, Si
Wafer input	standard wafer carriers, 25 slots, slot pitch ≥ 4.76mm
Wafer identification	laser mark scanner
Frame identification	2D barcode label (smart label optional)
Wafer orientation	automatically
Possitioning accuracy	X/Y direction: better than $\pm$ 1mm rotation: better than $\pm$ 1°
Lamination method	vacuum
Output system	industry standard wafer cassettes, automatic change over
Capacity	up to 50 wafers/hour
Bubbles	< 1% between wafer and film
Option	online 2D barcode label printer
Dimensions, weight (approx.)	1,280mm x 2,712mm $$ x 1,065mm (width x length x height) excluding jib-arm and operation panel, 2,000kg

Geringer Halbleitertechnik GmbH & Co. KG Liebigstraße 1 D-93092 Barbing, Germany

Phone: +49 (0) 9401.91 10 50 Fax: +49 (0) 9401.91 10 51 e-mail: geringer@geringer.de Internet: http://www.geringer.de/



Innovative production equipment for the semiconductor

The information in this specification consists only of general descriptions and / or performance features, which is not contractually binding. Any specific performance features / capabilities will only be binding, if contractually agreed. Subject to changes without notice. V1.2